External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.94131	100.0	1.1
			Subtotal	0.94131	100	1.1
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.06738	99.99	0.07874
			Subtotal	0.06739	100	0.07875
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00278	2.5	0.00325
		Paraffin wax	8002-74-2	0.00779	7.0	0.0091
		Epoxy resin system		0.02225	20.0	0.026
		Silver (Ag)	7440-22-4	0.07843	70.5	0.09165
			Subtotal	0.11125	100	0.13
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02612	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05224	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.20158	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.96262	97.55	59.55427
			Subtotal	52.24256	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48777	100.0	0.57
			Subtotal	0.48777	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.69225	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.38422	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.61176	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.4615	1.0	0.5393
			Subtotal	46.14973	100	53.93
			Total	100.00001	100	116.85875

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